9 Scientific publications 2002

Bertz, A.; Küchler, M.; Knöfler, R.; Gessner, T.: „A novel high aspect ratio technology for mems fabrication using standard silicon wafers“. Sensors & Actuators: A. Physical, Volume 97, Issue 1, 1 April 2002, Page 691; ISSN 0924-4247

Billep, D.: Mikromechanische Inertialsensoren, VDE Kongress 2002, 21.-23.10.2002 Dresden

Bohuslavová, A.; Schulz, S.E.; Gessner , T.: "Effect of PECVD SiO_2 AND Si_3N_4

Hard Mask Deposition on Mesoporous Silica Ultralow k Dielectric Films", Talk presented at "Materials for Advanced Metallization – MAM 2002", Book of Abstracts, FZ Jülich (2002), pp. 65/66.

Bruch, R.; Deshpande, K.; Merabet, H.; Picton, E.; Kondagari, S.; Otto, T.; Saupe, R.; Hientzsch, M.; Gessner, T.: "Vibrational Spectroscopy: A New Tool in Biomedical Diagnostics, 15. Internationale Wissenschaftliche Konferenz Mittweida, Wissenschaftliche Berichte, IWKM 2002

Dötzel, W.; Schröter, B.; Frühauf, J.; Mehner, J.; Gessner, T.: Movable Micromechanical Joints for Use in Micromechatronics. Proc. APEIE, Vol.1, pp. 4-8, Novosibirsk, 2002, ISBN 0-7803-7361-8

Ecke, R.; Schulz, S.; Gessner T.; Wenger, C.[1]; Wenzel C.1; Bartha, J.[1]; Hecker, M.[2]; Hübner, R.2; Mattern N.[2]; Wetzig, K.[2]; Engelmann, H.J.[3];
Zschech, E.3: "Ultrathin Diffusion Barriers for high-integrated Cu-Metallization", Tagung NanoDe 2002, Bonn 6. - 7.05.2002
1 TU Dresden, Institute for Semiconductor and Microsystem Technology
2 Institute for Solid State and Materials Research Dresden
3 Materials Analysis Department, AMD Saxony Manufacturing GmbH Dresden

Ecke, R.; Schulz, S.; Hecker, M.[1]; Engelmann, H.-J.[2]; Gessner, T.;
"Development of PECVD WN_x ultrathin film as barrier layer for copper metallization", MaterialsWeek 2002, München 30.09. - 2.10.2002
1 Institute for Solid State and Materials Research Dresden
2 Materials Analysis Department, AMD Saxony Manufacturing GmbH Dresden

Ecke, R.; Schulz, S.; Hecker1, M.; Gessner, T.: "Development of PECVD WN_x ultrathin film as barrier layer for copper metallization", Microelectronic Engineering 64 (2002) p. 261
1 Institute for Solid State and Materials Research Dresden

Erler, K.; Mrwa, A.; Diefenbach, K. H.; Ebest, G.; Werner, T.; Schwarz, T.:
„Application of cost effective solar cell processing steps on RIE textured silicon surfaces“, PV in Europe - From PV Technology to Energy Solutions Conference, V2.9, 07-11 october 2002, Rome

Flaspöhler, M.; Kuhn, M.; Kaufmann, C.; Guessous, F.; Frühauf, J.; Gessner, T.; Hübler, A.: "Image capturing method using a microactuator with diffraction grating", Actuator 2002, 8th International Conference on New Actuators, 10-12 June 2002, Bremen, Germany, Conference Proceedings 325-328

Frühauf, J.; Trumpold, H.: „Silicon Standards for Assessment and Calibration of Stylus Probes", Annals of the CIRP Vol. 51/1/2002, 475-478

Frühauf, S.; Streiter, I.; Schulz, S.E.; Brendler[3], E.; Himcinschi,C.; Friedrich, M.; Gessner, T.; Zahn, D.R.T.: "Hydrophobisation process for porous low k dielectric silica layers" , Conf. Proc. ULSI XVII, Materials Research Society, Warrendale (2002) 287-294.
[3] Institute of Analytical Chemistry, Freiberg University of Mining and Technology, Germany

Frühauf, S.; Streiter, I.; Schulz, S.E.; Gessner, T.; Matusche, J.; Schmidt, U.; Schuhbauer, A.: "Low-k Materials: Nanoporous SiO2-Layers with an ultra low dielectric constant", Poster presented at NanoDE 2002, May, 2002, Bonn, Germany

Frühauf, S.; Streiter,I.; Schulz, S.E.; Gessner,T.: "SiO_2-Xerogel-Dünnschichten als Isolatormaterial mit kleiner Dielektrizitätskonstante" , Beitrag zum Abschlusskolloquium des DFG-Graduiertenkollegs "Werkstoffphysikalische Modellierung", Juni (2002), Freiberg, Germany

Frühauf, S.; Streiter, I.; Rennau, M.; Puschmann, R. ; Schulz, S.E.; Gessner, T.; Chudoba, T.; Richter, F., Flannery, C[1].; Matusche, J.[2]; Schmidt.U.[2]: "Electrical and Mechanical characterization of porous silicon dioxide as an ultra low k dielectric", Talk presented at Materialsweek, Sept 30th – Oct 2nd , Munich, Germany
[1] Paul Drude Institute for Solid State Electronics, Berlin, Germany
[2] Applied Materials AG Europe, Dresden, Germany

Frühauf, S.; Streiter, I.; Puschmann, R.; Schulz, S.E.; Himcinschi, C.C.; Flannery, C. M.; Gessner, T.; Zahn, D.R.T.: "Modified silica xerogel as a low- dielectric with improved mechanical properties", Poster presented at the "Advanced Metallization Conference" (AMC), Oct 1-3, 2002, San Diego, USA

Gessner, T.; Schulz, S: "Copper and Low-k Technology for On-Chip Metallization", Invited Talk presented at "Flip-Chip & Chip Scale Europe 2002", March 20 - 21, Böblingen

Gessner, T.: "Transfer of Technology in the Semiconductor Industry: Science-Industry in Saxony", Forum in Tokio zur Präsentation des Forschungs- und Industriepotentials aus dem Freistaat Sachsen, Tokio, Japan, 14.02.2002

Gessner, T.: "Low temperature wafer bonding and AIM technology", Universitätskolloquium, NTU Singapore, 18.02.02

Gessner, T.: "Microsystems/MEMS devices fabricated by using silicon micromachining", öffentliches Universitätskolloquium, University of Nevada, Reno, USA, 12.04.2002

Gessner, T.: "Von der Mikro- zur Nanoelektronik - eine besondere Herausforderung für das Metallisierungssystem", Tagung NanoDe 2002, Bonn 6. - 7.05.2002

Gessner, T.: "Microsystem Research at the Chemnitz University of Technology", Universitätskolloquium, FUDAN University Shanghai, June 2002

Gessner, T.: "MEMS and Microsystem Technologies", Plenary lecture, Süss MicroTec Workshop "Trends in MEMS and Process Technology", Peking, China, 25. Oct. 2002

Gessner, T.: “Von der Mikro- zur Nanotechnologie - eine besondere Herausforderung für die Systemintegration“, Silicon Saxony Kolloquium, Dresden, Germany, November 2002

Hanf, M.; Kurth, S.; Faust, W.; Billep, D; Hahn, R.; Heinz, S.; Dötzel, W.; Gessner, T.: Realization of a Hadamard transform optic using a micromirror array for light modulation, OPTO 2002, Proceedings, Erfurt 2002, pp. 63-66

Hanf, M.; Bennini, F.; Frühauf, J.; Gärtner, E; Dötzel, W.: Realization of Electrostatically Driven Actuators Using Curved Electrodes Fabricated Using Silicon Bulk Micromachining Techniques, ACTUATOR 2002, 8th International Conference on New Actuators, Bremen June 2002, pp. 329-332

Hecker, M.[1]; Hübner, R.[1]; Ecke, R.; Schulz, S.; Engelmann, H.-J.[2]; Stegmann, H.[2]; Hoffmann, V.[1]; Mattern, N.[1]; Gessner, T.; Zschech, E.[2]: "Effect of annealing on the microstructure of ultrathin tungsten nitride diffusion barriers for copper metallization", Microelectronic Engineering 64 (2002) p. 269
1 Institute for Solid State and Materials Research Dresden
2 Materials Analysis Department, AMD Saxony Manufacturing GmbH Dresden

Himcinschi, C.[1]; Friedrich, M.[1]; Frühauf, S.; Streiter, I.; Schulz, S.E.; Gessner, T.; Baklanov, M.R.[2]; Mogilnikov, K.P.[2]; Zahn, D.R.T.[1]: “ Ellipsometric study of the change in the porosity of silica xerogels after chemical modification of the surface with hexamethyldisilazane ”, Anal Bioanal Chem 374 (2002) 654–657.
[1] Institute of Physics, Chemnitz University of Technology, D-09107 Chemnitz, Germany
[2] XPEQT at IMEC, B-3001 Leuven, Belgium

Hoffmann, R.; Gottfried, K.; Vogel, M.; Streit, A.; Dieckmann, F.; Dietel, U.: "Bestimmung der Konzentration von limitierten gasförmigen Schadstoffkomponenten im Abgas von Verbrennungsmotoren durch Vollstrommessung mit Titanoxidgassensoren", MTZ Motortechnische Zeitschrift 5/2002 Jahrgang 63, Seite 400 ff., Wiesbaden, ISSN 0024-8525

Hoffmann, R.; Gottfried K.; Kaufmann C.; Gessner, T.; Vogel, M.; Dietel, U.: "Testing of a Gas Sensor for High Temperature Application" ,"MATERIALS WEEK 2001 - Proceedings"; Ed. Werkstoffwoche-Partnerschaft GbR, Publisher: Werkstoff-Informationsgesellschaft mbH, Frankfurt, 2002, ISBN 3-88355-302-6

Jänsch, E.; Gärtner, E.; Frühauf, J.: „Biegebruchfestigkeiten von geätzten und verformten Silicium-Mikrostrukturen“, Freiberger Forschungshefte B321 Werkstofftechnologie (2002) „Kristallisation und Technik“, S. 238-253, Herausgeber: H.-J. Möller, E. Buhrig und Rektor der TU Bergakademie Freiberg (2002), ISBN-Nr. 3-86012-173-1

Jung, E,; Wiemer, M.; Grosser, V.; Bock, K.; Wolf, J.: “Packaging for MEMS devices - stumbling block or enabling solution? “, DTIP 2002, Cannes, in press

König, D.; Ebest, G.: „Novel external drift field source by localization of electrons for improvement of solar cells“, Solar Energy Materials and Solar Cells 75, 335 (2002)

König, D.; Ebest, G.: „New contact frame design for minimizing losses due to edge recombination and grid-induced shading“, Solar Energy Materials and Solar Cells 75, 381 (2002)

König, D.; Scholz, R.; Gemming, S.; Thurzo, I.; Kampen, T. U.; Zahn, D. R. T.; Ebest, G.: „Evidence for high negative charge densities in AlF3 coatings on oxidized silicon: a promising source for large drift fields“, Physica E 14, 259 (2002)

Korndörfer, F.; Heinz, S.; Zeun, H.; Ebest, G.: „Specifics of high voltage technologies - Characterization and modeling of HV-DMOS transistors“, Proceedings Conference Applied Electronics 2002, pp. 114-117, 11.-12.09.2002 Pilsen Tschechien, ISBN 80-7082-881-1

Kuhn, M.; Flaspöhler, M.; Krönert, S.; Geßner, T.; Hübler, A.; Frühauf, J.: "Optische Gitter auf Mikroaktuatoren - Herstellung und Einsatz", Scientific Reports: Journal of the University of Applied Sciences Mittweida, No. 10, 2002, p. 167-172, ISSN 1437-7624

Lohmann, Ch.; Bertz, A.; Küchler, M.; Reuter, D.; Geßner, T.: “Eine neue HIGH–ASPECT–RATIO–Technologie für die MEMS-Integration“. 15. International Scientific Conference Mittweida, Nov. 7-9 2002; Heft 10 2002, pp. 156-161; ISSN 1437-7624

Mehner, J.; Bennini, F.; Dötzel, W.: Methods and Tools to Design Microsystems, First International Symposium on Mechatronics (ISOM 2002), Chemnitz, Februar 2002, pp. 473-482, ISBN 3-00-007504

Mrwa, A.; Erler, K.; Diefenbach, K. H.; Ebest, G.: „Rapid and classic thermal processing of block cast multicrystalline and edge defined film-fed growth EFG silicon“, PV in Europe - From PV Technology to Energy Solutions Conference, V2.8, 07-11 October 2002, Rome

Mrwa, A.; Erler, K.; Ebest, G.; Steckemetz, S.; Hezel, R.: „RT Annealed Spin-on Glass Process for Screen Printed Multicrystalline Silicon Solar Cells“, World Renewable Energy Congress VII, Poster, Cologne 2002

Murray, C.; Flannery, C.; Streiter, I.; Schulz, S.E.; Baklanov, M.R.; Mogilnikov, K.P.; Himcinschi, C.; Friedrich, M.; Zahn, D.R.T.; Gessner, T.: “Comparison of Techniques to Characterise the Density, Porosity and Elastic Modulus of Porous Low-k SiO2 Xerogel Films, Microelectronics Engineering 60 (2002), 133-141**.**

Otto, T.; Saupe, R.; Gessner, T.: “Development of a Microspectrometer for the Infrared Range”, “IRMMW 2002" September 22 – 26, 2002, San Diego CA, Conference Digest, IEEE Catalog Number 02EX561, pp. 31-32

Otto, T.; Saupe, R. Müller, A., Gessner, T.: "Infrarotspektroskopie unter Einsatz mikrosystemtechnischer Komponenten", 15. Internationale Wissenschaftliche Konferenz Mittweida, Mittweida, Wissenschaftliche Berichte, IWKM 2002, Nr. 10, pp. 180-184

Petzold, M.; Katzer, D.; Wiemer, M.; Bagdahn, J.: “Strength and long-term reliability testing of wafer-bonded MEMS”,DTIP 2002, Cannes, in press

Saupe, R.; Otto, T.; Gessner, T.: “Design and Packaging of Ultracompact Infrared Spectrometers Using Micromechanical Components”, International Conference Infrared Sensors and Systems, IRS² Proceedings 2002, pp. 237-242

Scheibner, D.; Mehner, J.; Brämer, B.; Dötzel, W.; Gessner, **T.:** Wide Range Tunable Resonators for Vibration Measurements, MNE 2002, Lugano, September 16-19, 2002

Scheibner, D.; Wibbeler, J.; Mehner, J.; Brämer, B.; Dötzel, W.; Gessner, **T.:** Frequency-Selective Silicon Vibration Sensor with Direct Electrostatic Stiffness Modulation, DTIP 2002, Cannes, May 6-8, 2002, pp. 325-332, ISBN 0-8194-4518-5

Scheibner, D.; Wibbeler, J.; Mehner, J.; Brämer, B.; Dötzel, W.; Gessner, **T.:** Frequency Selective Sensor Arrays for Vibration Measurement, IEEE Sensors 2002, Orlando, June 11-14, 2002, ISSN 0-7803-7455-X

Scheibner, D.; Wibbeler, J.; Mehner, J.; Dötzel, W.; Gessner, **T.:** Silicon vibration sensor arrays with electrically tunable band selectivity, Microsystem Technologies 8 (2002) 4-5, 314-317; DOI 10.1007/s00542-002-0100-2

Schröter, B.; Frühauf, J.; Mehner, J.; Dötzel, W.; Gessner, **T.:** Flexible Gelenke in der Mikromechanik, First International Symposium on Mechatronics (ISOM 2002), Chemnitz, Februar 2002, pp. 530-535, ISBN 3-00-007504-6

Schröter, B.; Frühauf, J.; Mehner, J.; Gessner, T.; Dötzel, W.: Feinwerktechnische Wirkprinzipien in der Mikrosystemtechnik. Proc. 47. Int. Wiss. Kolloquium, Ilmenau, 2002, ISSN 1619-4098

Streiter, R.; Wolf, H.; Zhu, Z.; Xiao, X.; Gessner, T.: "Thermal and Electrical Simulation of Deep Submicron Interconnection Systems", Proc. Advanced Metallization Conference 2001 (AMC 2001), Montreal, Canada, Oct. 9-11, 2001, Materials Research Society, Warrendale, 2002, pp. 379-386.

Streiter, R.; Wolf, H.; Belsky, P.; Tirschler, W.; Giegengack, H.; Urbansky, N.; Gessner, T.: "Influence of target texture on the deposition of titanium films by long throw sputtering", presented at the Advanced Metallization Conference 2002 (AMC 2002), San Diego, California, Oct. 1-3, 2002.

Thurzo, I.; Kampen, T. U.; Zahn, D. R. T.; König, D.: „Electron capture kinetics at AlF_3/SiO_2 interfaces", Oral session ThA15.15, ICSFS-11, 8 - 12 July 2002, Marseille, France

Uhlig, M.; Zacher, M.; Bertz, A.; Werner, T.; Gessner, T.: „Organische Low-k-Materialien für die Mikroelektronik", Proceedings vom: 3.Woerlitzer Workshop Funktionelle Schichten „Organische Schichten für Elektronik und Optoelektronik", Wörlitz, 14./15. Mai 2002,

Uhlig, M.; Bertz, A.; Brocke, H.; Dobler, M.; Flannery, C.; Jnawali, G.; Zeidler, D.; Gessner, T.: „Integration of Plasma Deposited CF Polymer in a Copper / Low *k* Damascene Architecture", Proc. Advanced Metallization Conference (AMC 2002), Oct. 1-3, 2002, San Diego, California, Materials Research Society, Warrendale

Wiemer, M.; Frömel, J.; Gessner, T.: "Applikationsfelder für Waferbondverfahren in der Mikromechanik und Mikroelektronik", Festschrift für Prof. Meusel – TU Dresden, 2002

Wiemer, M. ; Gessner, T.: "MEMS-Packaging", News Letter Süss Microtec,

Wiemer, M. ; Gessner, T.: "Assembly and Bonding Technologies for Wafer Level Integration", VTE Heft 6, DVS-Verlag, 2002

Wolf, H.; Streiter, R.; Tirschler, W.; Giegengack, H.; Urbansky, N.; Gessner, T.: "Investigation of long throw PVD of titanium films from polycrystalline targets with texture", Microelectron. Eng. 63/4 (2002) 329-345.

Zimmermann, S.; Baumann, J.; Kaufmann, C.; Gessner, T.: „Thermal stability of thin Ta and TaN_x films as diffusion barriers for copper metallization", Poster presented at the „Advanced Metallization Conference (AMC) ", October 1-3, 2002, San Diego, USA

10 Guests & special international relations

Guests from:

February

- Prof. Frühauf: VEECO-Workshop "Surface Profiling by Tactile and Optical Instruments", 26 participants and 3 tutors (Dr. Volz, Mr. Weinbach, Mr. Trenkler)
- Fed. Dept. of Defense, USA: Scientists and Manager of the US Air Force, US Navy and Pentagon

March

- Mrs. Prof. Schmidt-Landsiedel, TU Munich, Germany

April

- Members of Nanometrics , USA
  Dr. H.-J. Sterzel, Dr. L. Wittenbecher, BASF AG, Germany

May

- Doz. Dr.-Ing. Jan Mühlbacher TU Pilsen, Czech Republic
  Doz. Dr.-Ing. Vaclav Kus TU Pilsen, Czech Republic
  Doz. Dr.-Ing. Vlastimil Skocil TU Pilsen, Czech Republic
- Dr. Tomasz S. Wolski, Technical University of Lodz, Poland
- Prof. James E. Morris, Portland State University, Portland, Oregon

June

- Prof. Reinhard Bruch, University of Nevada, Reno, USA

July

- Prof. Ruan Gang, Fudan University, Shanghai, China July – September 2002
  Consultant Professor of the Faculty of Electrical Engineering and Information Technology, Chemnitz University of Technology
- Prof. James Lu, Rensselear Polytechnic Institute, Troy NY, USA (8.7.2002)
- Prof. Mikhail Baklanov, XPEQT/IMEC, Belgium (10.7.2002)
- Southwest University of Science and Technology, Electronics Engineering College: Prof. Jian Zhang, Prof. Wei Su, Prof. Xiaoping He (15.7.2002)
- Mr. Meng Shuguang (Counsellor of the P.R. Chinese Embassy in Germany), Mr. Pan Zhanfu (Secretary for Science and Technology), (23.7.2002)

August

- Dr. Walter Huber, Dr. Michl Laimer, Prof. Dr. Konrad Bergmeister
  Landesagentur Umwelt, Bozen, Italien
- Hebei Semiconductor Research Institute, P.R. China (6.8.2002)
  Prof. Zhou Chunlin (Vice-President), Dr. Yang Yongjun, Liu Chenhui, Liu Yongli
- Dr. Li Gong, Chief-Representative Suss MicroTec AG Shanghai, P.R. China (6.8.2002)
- Dr. Hannes Richter, Hermsdorfer Institut für Technische Keramik e.V. (8.8.2002)
- Jay Rohde, TPS Manager, CMP, Applied Materials, USA (15.8.2002)

September

- Applied Materials Europe, Europe Technology Development (12.9.2002)
  Dr. Patrick Rabinzohn (General Manager) & Dr. Ursula Schmidt (Technologist)

October

- Prof. Shiyang Zhu, FUDAN University, Shanghai, China
- Umesh Bhandary, Applied Materials, Interconnects Systems & Modules, USA (8.10.2002)

November

- Prof. Dr. Ngyyen, Nam Trung; Technological University of Singapore

December

- Konstantin Smekalin, Applied Materials, Interconnects Systems & Modules, USA (4.12.2002)
- Dr. Gustafson, NEXX, USA & Mr. P. Hilbig, TELTEC (10.12.2002)

and

Dr. Manfred Reiche	Max-Plank-Institut für Mikrostrukturphysik
Dr. Jürgen Leib	Schott Glas Electronic Packaging
Wolfgang Freese &	Wirtschaftsförderung Sachsen
Prof. Dr. Dieter Landgraf-Dietz	
Dipl.-Ing. Jian Zu &	Delegation of German Industry & Commerce Shanghai
Dipl.-Ing. Min Shi	
Dr. Toshihiro Itoh	University of Tokyo
Gang Hu	Microelectronic Communication Trust
Dr. Ursula Schmidt	Applied Materials Europe
Dipl.-Ing. Winfried Rabe	ATMEL Wireless & µC
Dipl.-Ing. Roy Knechtel	X-Fab
Dr. Franz Richter &	Süss Microtec
Dipl.-Wirtschaftsing. Rolf Wolf	
Dr. Wolfram Geiger	LITEF
Heinrich Hippenmeyer & Co.	SICK
Dr. JianQiang Lü	Rensselaer Polytechnic Institute

Visit to:

Dr. S.E. Schulz	Hitachi Hitech, Sanyo, Epson, Matsushita (Japan)	27.-31.1.2002
Dr. S.E. Schulz	Solid State Measurements, Pittsburgh PA, USA	29./30.9.2002
Prof. T. Gessner	Singapore & Tokyo	February 2002
Prof. T. Gessner	Applied Photonics Worldwide Inc., Reno	April 2002
Prof. T. Gessner,	Applied Materials, Santa Clara, USA	April & Oct. 2002
Prof. T. Gessner,	Advanced Metallization Conference	1.-3.10. 2002
Dr.S.E.Schulz, M. Uhlig	AMC 2002, San Diego, USA	
Prof. T. Gessner,	TSINGHUA University , Beijing	June 2002
Dr. R. Streiter,	FUDAN University & Pudong	
Dr. T. Otto	Official Opening Ceremony of the FhG-IZM office in Shanghai	
Prof. T. Gessner	Chongqing, China	December 2002
Dr. R. Streiter	4th China HiTec Fair	
Dr. T. Otto		

Prof. W. Dötzel, Dr. R. Kiehnscherf	Novosibirsk Technical University, Russia	September 2002
Prof. W. Schufft, Dr. R. Kiehnscherf	TU Pilsen, Czech Republic	May 2002

Scientific coworkers / PhD:

Rüdiger Frank	Germany, Universität Tübingen 1st October 2001 – 28th February 2002
Mrs. Xiao Xia	China, FUDAN-University , Shanghai 1st November 1997 – 31st March 2002
Prof. David Wei Zhang	China, FUDAN- University, Shanghai 1st October 2000 – 31st May 2002
Prof. Dr. Banmali S. Rawat	USA, University of Nevada, Reno May – August 2002
Prof. Ruan Gang	China, FUDAN University, Shanghai July – September 2002
Ji Yinhu & Cheng Ping & Li Chuan	China, FACRI Institute, Xi´an July – October 2002
DI Alexej Schaporin	Novosibirsk Technical University, Russia November 2002 – October 2003
DI Wladimir Kolchuzhin	Novosibirsk Technical University, Russia November 2002 – October 2003
Prof. Zhengzhu Fan Yiqiong Shao Yan Yuntao et al	China, FACRI Institute, Xián October 2002 – December 2002
Ms. Prof. Jia Zhou	China, FUDAN University, Shanghai August 2002 – July 2003

Students:

Radim Hrusa	TU Pilsen	08/2001 – 01/2002
Martin Škopek	TU Pilsen	10/2001 – 01/2002
Rostislav Vlk	TU Pilsen	10/2001 – 01/2002
Petr Belsky	TU Pilsen	10/2001 – 03/2002
Jan Blazek	TU Pilsen	01/2002 – 04/2002
Marta Poubova	TU Pilsen	03/2002 – 08/2002
Karel Besorna	TU Pilsen	03/2002 – 03/2003
Mariusz Patecki	TU Lodz	10/2002 – 04/2003
Jia Chenping	University of Xian, China	10/2001 – 06/2003
Eran Lipp	Technion-Israel Institute of Technology, Haifa, Israel	10/2002
Sachin Singh	University of Nevada, Reno, USA	05/2002 – 10/2002
Rashmi Bahuguna	University of Nevada, Reno, USA	05/2002 – 10/2002